

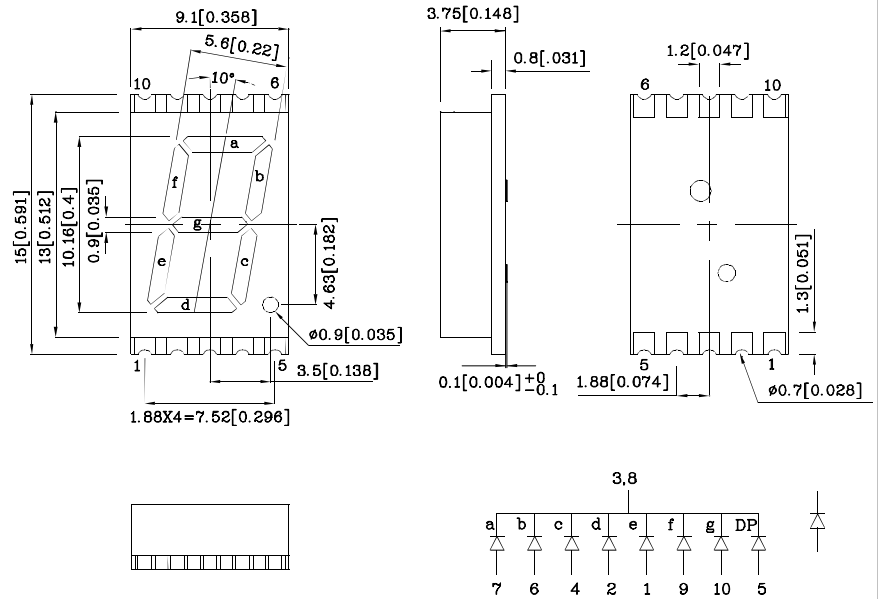
Features

- 0.4 inch digit height
- Robust package
- Low power consumption
- Standard configuration: Gray face w/ white segments
- Standard Package: 400pcs/ Reel
- MSL (Moisture Sensitivity Level): 2a
- RoHS compliant



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

Package Schematics



Notes:

1. All dimensions are in millimeters (inches), Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
2. Specifications are subject to change without notice.
3. The gap between the reflector and PCB shall not exceed 0.25mm.

Absolute Maximum Ratings (T _A =25°C)		Blue (InGaN)	Unit
Reverse Voltage	V _R	5	V
Forward Current	I _F	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i _{FS}	100	mA
Power Dissipation	P _D	120	mW
Operating Temperature	T _A	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +85	
Electrostatic Discharge Threshold (HBM)		1000	V

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

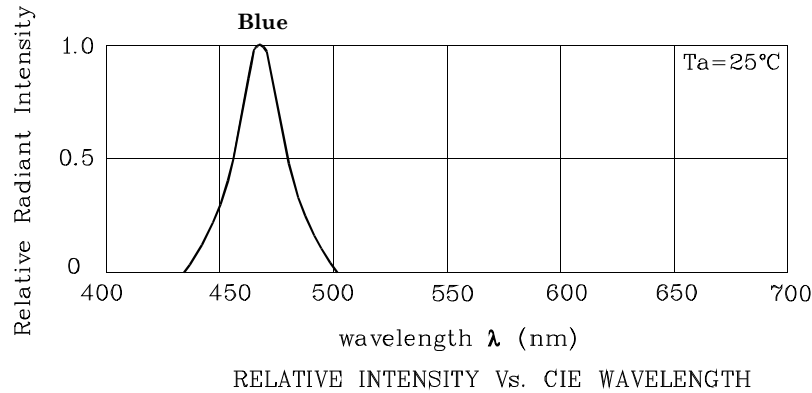
Operating Characteristics (T _A =25°C)		Blue (InGaN)	Unit
Forward Voltage (Typ.) (I _F =10mA)	V _F	3.05	V
Forward Voltage (Max.) (I _F =10mA)	V _F	4	V
Reverse Current (Max.) (V _R =5V)	I _R	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =10mA)	λ _P	468*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =10mA)	λ _D	465*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	Δλ	21	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	C	100	pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity CIE127-2007* (I _F =10mA) ucd		Wavelength CIE127-2007* nm λP	Description
			min.	typ.		
XZFBBA10C	Blue	InGaN	2200*	5190*	468*	Common Cathode, Rt.Hand Decimal.

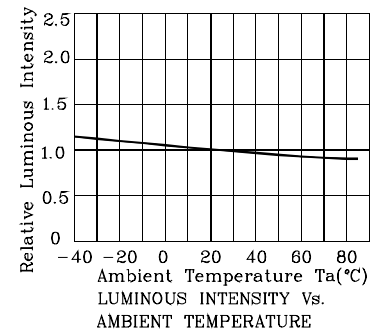
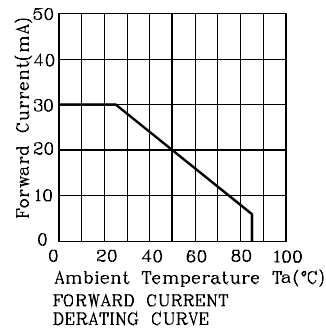
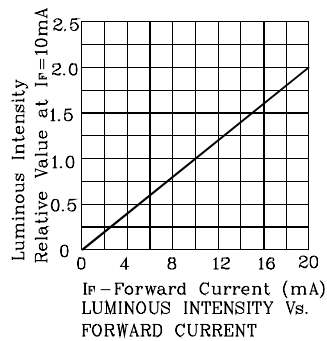
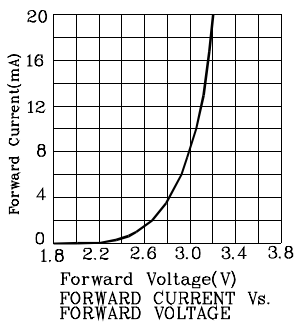
*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

Oct 13,2016

XDSA9141 V8-Z Layout: Maggie L.

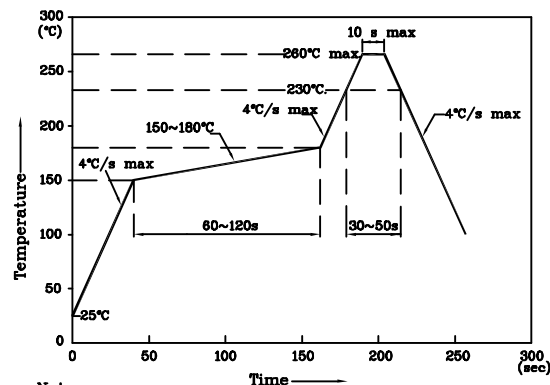


❖ Blue



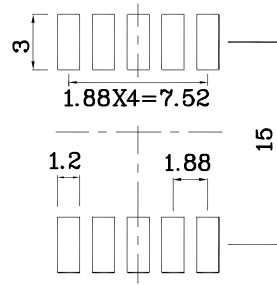
LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

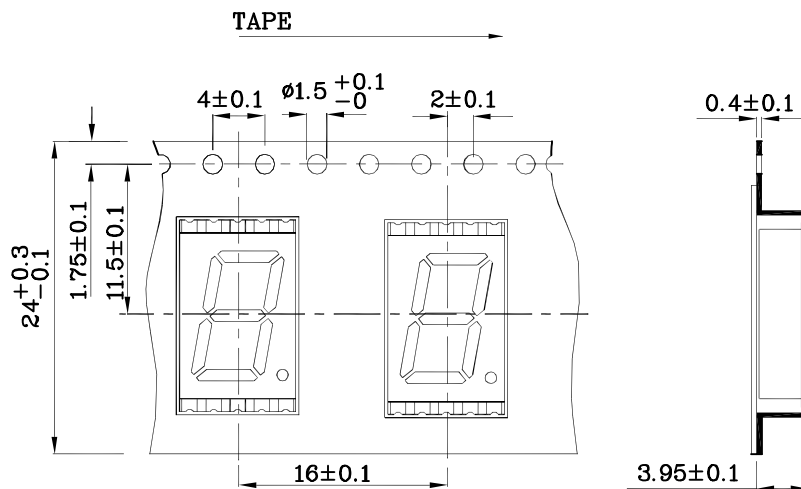


1. Maximum soldering temperature should not exceed 260°C
2. Recommended reflow temperature: 145°C-260°C
3. Do not put stress to the epoxy resin during high temperatures conditions

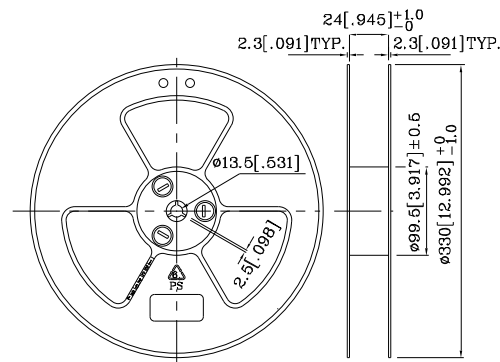
❖ Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.15)



❖ Tape Specification (Units : mm)



❖ Reel Dimension



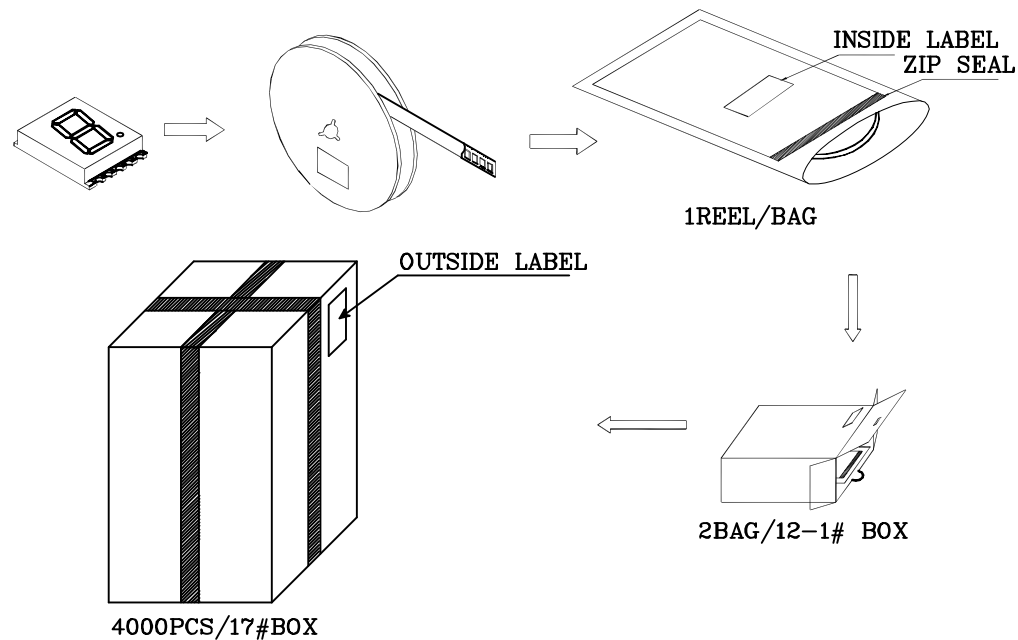
Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

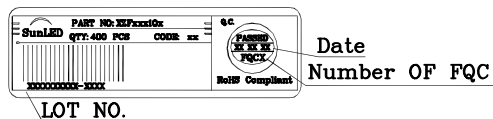
1. Wavelength: ± 1 nm
2. Luminous intensity / luminous flux: $\pm 15\%$
3. Forward Voltage: ± 0.1 V

Note: Accuracy may depend on the sorting parameters.

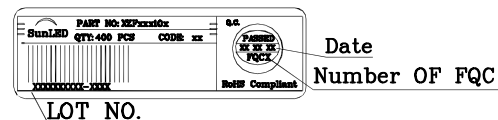
PACKING & LABEL SPECIFICATIONS



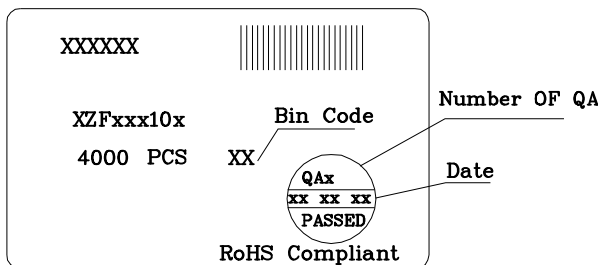
Inside Label On tape



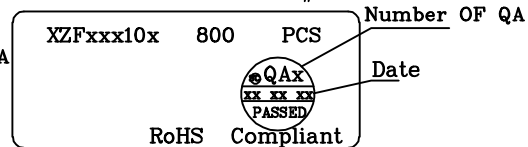
Outside Label On Bag



Outside Label On 17#Box



Outside Label On 12-1#Box



TERMS OF USE

1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
2. Contents within this document are subject to improvement and enhancement changes without notice.
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